CxO Summit

Welcome Remarks

L. Altimime
President
SEMI Europe, Berlin, Germany

Abstract
Coming Soon

Biography
Laith Altimime, as President of SEMI Europe, leads SEMI's activities in Europe and the Middle East and Africa (EMEA). Altimime has P&L responsibility as well as ownership of all Europe region programs and events, including SEMICON Europa. He is responsible for establishing industry standards, advocacy, community development, expositions, and programs. He provides support and services to SEMI members worldwide that have supply chain interests in Europe. He manages and nurtures relationships with SEMI members in the region and globally as well as with local associations and constituents in industry, government, and academia. Altimime has more than 30 years of international experience in the semiconductor industry. Prior to joining SEMI in 2015, He held senior leadership positions at NEC, KLA-Tencor, Infineon, Qimonda, and imec. Altimime holds an MSc from Heriot-Watt University, Scotland.

References

Opening Remarks

A. Manocha
President and Chief Executive Officer
SEMI, Milpitas, United States of America

Abstract
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Biography
Ajit Manocha is the president and CEO of SEMI, the global industry association serving the semiconductor and electronics manufacturing and design supply chain. Throughout his career, Manocha has been a champion of industry collaboration as a critical means of advancing technology for societal and economic prosperity. In his leadership role at SEMI, Manocha has broadened the association's scope to fuel industry growth and foster collaboration on challenges such as geopolitical and sustainability concerns, the talent gap and supply chain disruptions. He has driven SEMI to evolve with the global microelectronics ecosystem as it rapidly expands to support smarter, connected applications based on artificial intelligence, machine learning and other disruptive technologies. Manocha was formerly CEO at GlobalFoundries. Prior to this, he held the role of Executive VP of worldwide operations at Spansion and earlier served as Executive VP and chief manufacturing officer (chief operations officer) at Philips Semiconductors. He began his career at AT&T Bell Laboratories as a research scientist and was granted more than a dozen patents related to semiconductor manufacturing processes that served as the foundation for modern microelectronics manufacturing. He has served on the boards of SEMI, the Semiconductor Industry Association (SIA) and Global Semiconductor Alliance (GSA). Manocha has overseen the formation of more than 20 joint ventures and M&As over his career. Out of these, some of the most noteworthy are the manufacturing JV between AT&T and Cirrus Logic, the foundry JV SSMC between Philips Semiconductors and TSMC, the back-end JV Suzhou ASEN Semiconductors between Philips Semiconductors and ASE, and the spinoff of Philips Semiconductors (now NXP Semiconductors) from Royal Philips Electronics. Manocha served on President Obama's committees for "Advanced Manufacturing Partnerships" and the President's Council of Advisors on Science & Technology (PCAST). Manocha holds the rare distinction of being inducted into two Hall of Fames. In 2021, VLSIresearch (now TechInsights) added Manocha to its Semiconductor Industry Hall of Fame for his leadership of SEMI efforts to address geopolitical trade tensions as well as for his initiative in navigating the many challenges of the COVID-19 pandemic impacting SEMI and the microelectronics industry. In 2020, Manocha was inducted into the Silicon Valley Engineering Hall of Fame, and VLSIresearch named him an "All Star of the Semiconductor Industry" for his visionary leadership in 2019 to restructure SEMI to represent the expanded electronics supply chain.

References

Chips Act 2.0: How can Europe turn semiconductor excellence into investment, scale and resilience?



O. Schenk
Member of the European Parliament, Dresden, Germany

Abstract
Europe has many of the ingredients for semiconductor leadership: world-class research, strong industrial clusters and global champions in critical parts of the value chain. Yet too often, Europe struggles to turn these strengths into investment, scale and new industrial capacity. As the European Parliament begins to shape its position on Chips Act 2.0, the debate must therefore go beyond individual fabs, funding targets and market shares. The real challenge is to build a stronger European semiconductor ecosystem: connecting clusters across borders, bringing research faster to market, mobilising private investment and developing capabilities where strategic dependencies remain. With AI transforming the global geopolitical landscape at unprecedented speed, Europe must decide where it wants to lead, where it needs greater resilience and what it will take to remain a strong global technology player. Chips Act 2.0 is an opportunity to make those strategic choices.

Biography
Oliver Schenk has been a Member of the European Parliament since 2024 and serves as rapporteur in the Committee on Industry, Research and Energy for the Chips Act 2.0. In this role, he is leading the Parliament's work on Europe's future semiconductor policy. Before entering the European Parliament, he served from 2017 to 2024 as a Minister of State in Saxony and Head of the Saxon State Chancellery, including responsibility for European and federal affairs. Over the course of his career, he has held senior positions in both state and federal government, including in the fields of policy planning, digitalisation and technology. His work focuses on strengthening Europe's industrial competitiveness and technological resilience.

References

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A. Kumar Sinha
Additional Secretary, Ministry of Electronics and Information Technology (MeitY), Government of India, and Chief Executive Officer of the India Semiconductor Mission (ISM, Delhi, India

Abstract
Coming Soon

Biography
Shri Amitesh Kumar Sinha is Additional Secretary, Ministry of Electronics and Information Technology (MeitY), Government of India, and Chief Executive Officer of the India Semiconductor Mission (ISM). He also oversees Research and Development (R&D) in Electronics, contributing to India's strategic priorities in advanced technology, innovation and domestic manufacturing.

As CEO of the India Semiconductor Mission, he is key bureaucrat in driving India's semiconductor strategy and translating national semiconductor policy objectives into investments, manufacturing capabilities and ecosystem development. Under his leadership at ISM and MeitY, India has approved 12 semiconductor projects. His focus extends to strengthening domestic capabilities in Semiconductor manufacturing, chip design, semiconductor equipment, materials, talent development and supply chains, while facilitating technology partnerships and global industry collaboration.

Mr. Sinha has previously served as Joint Secretary in MeitY and the Ministry of New and Renewable Energy, and as Director in the Cabinet Secretariat. He has also held key operational and administrative positions across the Indian Railways.

He is at the forefront of India's efforts to build a globally competitive, resilient and innovation-driven semiconductor ecosystem, positioning India as a trusted partner in the global semiconductor value chain through international cooperation, technology collaboration and strategic industry partnerships.

References

Orchestrating a scalable AI revolution



L. Van den hove
Chairman
imec, Heverlee, Belgium

Abstract
Artificial intelligence is becoming the defining technology of our era, but its long-term impact depends on one critical challenge: scalability. As AI evolves toward complex, agentic systems operating from cloud to edge, demands on compute, memory, and connectivity are growing at an unprecedented pace. This keynote explores how sustaining the AI revolution requires innovation across the entire technology stack, from advanced CMOS and heterogeneous integration to photonic interconnects and system-level co-optimization. Looking further ahead, emerging paradigms such as quantum and brain-inspired computing may unlock new forms of efficient intelligence. Ultimately, scalable AI will not emerge from a single breakthrough, but from orchestrating a global ecosystem of technologies, disciplines, and innovators

Biography
Luc Van den hove is President and CEO of imec since July 1, 2009. Before he was executive vice president and chief operating officer. He joined imec in 1984, starting his research career in the field of silicide and interconnect technologies. In 1988, he became manager of imec’s micro-patterning group (lithography, dry etching); in 1996, department director of unit process step R&D; and in 1998, vice president of the silicon process and device technology division. In January 2007, he was appointed as imec's EVP & COO. Luc Van den hove received his PhD in electrical engineering from the KU Leuven, Belgium.
In 2023, he was honored with the Robert N. Noyce medal for his leadership in creating a worldwide research ecosystem in nanoelectronics technology with applications ranging from high-performance computing to health.
In 2025, he received an honorary distinction from the Flemish Community in recognition of his impressive role in strengthening Flanders as a leading innovative region. He has authored or co-authored more than 200 publications and conference contributions.
Starting in April 2026, he took on a new role as Chair of imec’s Board of Directors.

References

Navigating the Perfect Storm: Why the Future of AI Depends on Manufacturing Innovation



B. Schmidt
CTO
TRUMPF, Ditzingen, Germany

Abstract
Artificial intelligence is fueling an unprecedented global semiconductor ramp. Around the world, new fabs, pilot lines, research centers and innovation ecosystems are being launched at remarkable speed.
At the same time, the industry is entering one of its most significant technological transitions in decades. For years, progress was driven primarily by transistor scaling and shrinking feature sizes. Today, a fundamental question is emerging: *What will ultimately enable the next generation of AI?*

[From Scaling to Systems]

The industry's attention is widening from compute alone toward broader system architectures.
Advanced Packaging, including hybrid bonding, co-packaged optics, new materials and increasingly complex manufacturing processes, is becoming a decisive differentiator. The future will not be determined solely by how small we can make transistors, but by how effectively we connect chips, move data, manage heat and integrate entirely new system architectures. This transition represents one of the most profound shifts the semiconductor industry has experienced in decades.

[Europe's Opportunity in the Age of AI]

For Europe, this transformation creates a unique opportunity. Europe holds world-class positions in many of the technologies that make next-generation semiconductors possible: optics, photonics, laser and plasma technologies, metrology, materials engineering, power electronics and semiconductor manufacturing equipment. Across industrial clusters such as Leuven, Dresden and Eindhoven, Europe has built capabilities that are deeply embedded in the global semiconductor ecosystem. The opportunity is not only to contribute technologies, but to help shape how future semiconductor systems are designed and manufactured.

[With Speed and Collaboration to Industrial Impact]

The challenge is not a lack of innovation. The challenge is transforming innovation into industrial impact at the speed required by a rapidly changing market.
At the same time, global competition is intensifying. New semiconductor research centers, pilot lines and innovation ecosystems are emerging around the world. Europe's success will increasingly depend on how effectively we connect research and industry, accelerate technology transfer, shorten innovation cycles and build industrial momentum.
EUV has demonstrated that breakthrough innovation emerges when complementary capabilities are connected through trust, long-term commitment and shared ambition. Replicating this success in the next wave of semiconductor innovation will require strong public-private partnerships that create trusted environments for collaboration, accelerate technology transfer and bridge the gap between research

excellence and industrial deployment.
Success will also require Europe to rediscover some of the entrepreneurial strengths that once defined its industrial leadership: the willingness to act decisively, move quickly and embrace calculated risk. In an increasingly competitive global environment, research institutions and industry must work together with greater urgency and shared purpose, as has become common practice in several Asian innovation ecosystems.

[Creating the Conditions for Indispensability]
Europe's greatest opportunity in the age of AI is not to achieve technological independence, but to remain technologically indispensable. Governments must take a more entrepreneurial approach to enabling industrial progress. Beyond funding, Europe will need faster decision-making, more agile regulatory frameworks and a reduction in administrative barriers. In a race defined by speed of execution, the ability to create competitive framework conditions quickly may become as important as technological excellence itself.

Biography
Dr. rer. nat. Berthold Schmidt
Chief Technology Officer (CTO)
Member of the Managing Board of TRUMPF SE + Co. KG
Head of Corporate Technology & New Business, Electronics Division, EUV Division, and New Sectors.
Born in 1968 in Würzburg. Studied physics at the University of Würzburg and earned his doctorate at the Technical University of Munich.
In 2013, joined TRUMPF Laser Marking Systems in Grüsch, Switzerland, in the Research and Development department.
2015: Director of the Central Department of Corporate Research at TRUMPF GmbH + Co. KG, Ditzingen.
2016: CEO of TRUMPF Photonics Inc. in Cranbury, NJ (USA).
2017: Also CTO of TRUMPF Laser Technologie GmbH, Ditzingen.
From 2020 to 2023, CEO of TRUMPF Photonic Components GmbH, Ulm.
Member of the Executive Board since July 2023.

References

Connecting Technology and Society: SCREEN's Vision for the Next Generation of Semiconductors



M. Goto
Representative Director, President and CEO
SCREEN Holdings Co., Ltd., Kyoto, Japan

Abstract
As AI and digital transformation accelerate demand for high-performance and sustainable semiconductor technologies, the industry faces unprecedented challenges in terms of power consumption, manufacturing complexity, and innovation speed.
In this keynote, Masato Goto, President and CEO of SCREEN Holdings Co., Ltd., will discuss how SCREEN Semiconductor Solutions Co., Ltd. is addressing these challenges through strategic partnerships and by developing advanced semiconductor manufacturing technologies.
SCREEN's growth strategy builds on its leadership in semiconductor manufacturing equipment while expanding its role in advanced packaging solutions for the AI era and its commitment to enable next-generation device architectures through innovations in wafer cleaning, lithography-related processes, wafer-to-wafer bonding, and panel-level packaging.
Global R&D collaborations with leading semiconductor innovation centers, including imec and CEA-Leti in Europe, provide the foundation for both cutting-edge innovation and sustainability solutions aimed at resource-efficient semiconductor manufacturing.

Biography
Masato Goto is the Representative Director, President and Chief Executive Officer of SCREEN Holdings Co., Ltd.
He joined Dainippon Screen Mfg. Co., Ltd. (now SCREEN Holdings) in 1990. He was stationed in the United States from 1995 to 2001, and in Europe from 2001 to 2009. During these 14 years overseas, he engaged in field engineering, helping clients achieve stable operation and improve productivity at their production sites, primarily through equipment setup and onsite maintenance.
After returning to Japan, he became the general manager of the production department, in charge of ensuring a stable supply of equipment to clients. From 2011, he served executive officer, senior executive officer, and vice president of Semiconductor Equipment Company, in series.
In 2019, he became the president of SCREEN Semiconductor Solutions. Utilizing the knowledge and experience accumulated over the years and with strong leadership, he continuously led sales to record highs.
In 2024, he was appointed the head of corporate strategy at SCREEN Holdings. For over a year, he led the portfolio management of group businesses.
He has served in his current role since June 2025.

References

Singapore's Semiconductor Ecosystem: Accelerating Innovation Through Strategic Partnerships



Y. Yee Chia
Deputy CEO & EVP SG Semiconductor
A*STAR, Singapore, Singapore

Institute of Microelectronics
A*STAR IME

Abstract
The semiconductor industry is experiencing an unprecedented acceleration in microelectronic technologies, driven by the explosive growth of artificial intelligence applications.

In response, Singapore has launched its SG Semiconductor initiative, building on a globally connected ecosystem to meet the industry's need for multidisciplinary expertise and specialized infrastructure that shortens time to market.

This keynote examines Singapore's position as a semiconductor hub, its holistic, ecosystem-based approach, and its role as a technology accelerator across the value chain, from upstream to downstream. It highlights the core technology areas where Singapore is investing billions of dollars.

As the global race for semiconductor leadership intensifies, no company, whether a multinational or a small or medium-sized enterprise, can succeed alone. Strong, trusted partnerships across industry, academia, and government are what will turn investment into lasting outcomes. The keynote closes with an explanation on how Singapore is working with partners worldwide to secure the future of the semiconductor value chain.

Biography
Professor Yeo Yee Chia leads Singapore's first RIE Flagship in Semiconductors and is A*STAR's Deputy Chief Executive (Innovation & Enterprise), helping to shape the future of one of Singapore's most strategically important industries. He is also Professor of Electrical Engineering at the National University of Singapore (NUS). An award-winning, internationally recognised semiconductor researcher, Professor Yeo has published over 700 research papers and is an inventor of over 400 US patents. More than 40 PhD students graduated under his tutelage.

Recognised with the Singapore Young Scientist Award in 2006 for his research in nanoelectronics and semiconductor devices, Professor Yeo went on to receive the National Research Foundation Fellowship (NRFF) in 2008. The Fellowship enabled him to establish an independent research programme at the National University of Singapore, where he pursued research in strain engineering for next-generation semiconductor manufacturing, deepening his work on transistor technologies aimed at enabling faster and more energy-efficient chips.

His research leadership later took him to TSMC, where he served as Director of Research and Development. Working at the forefront of semiconductor innovation, he co-developed TSMC's industry-leading 7 nm, 5 nm,

and 3 nm technologies, which have impacted the world in areas such as high performance computing, artificial intelligence, and consumer electronics.

Supported under the Returning Singapore Scientists Scheme, Professor Yeo returned to Singapore and joined A*STAR in 2022, bringing with him the experience of translating cutting-edge research into industrial innovation at global scale. Drawing on experience across academia, industry and national R&D, he now leads efforts to deepen Singapore's semiconductor capabilities, accelerate research translation, strengthen industry partnerships and nurture the next generation of scientific talent.

References

Powering the AI Era in Europe: From Semiconductor Innovation to Global Industrial Impact



S. Dauvé
CEO
CEA-Leti, Grenoble, France

Abstract
AI is entering a new era—one where the limits of computing are increasingly defined not only by algorithms, but by the technologies that power, connect and integrate them. The semiconductor industry is at the heart of this transformation. This keynote will explore how breakthrough innovation provided by European RTOs, from advanced silicon to heterogeneous integration and photonics, can unlock the next generation of AI systems while addressing the critical challenges of energy, scale and sustainability. It will also highlight the power of global collaboration to turn rapidly deep-tech innovation into industrial impact and shape the technological foundations of the AI era.

Biography
Sébastien Dauvé was named CEO of CEA-Leti effective on July 1, 2021, after more than twenty years of experience in microelectronics technologies and their applications, including clean mobility, medicine of the future, cybersecurity, and power electronics. Sébastien Dauvé started his career at the French Armament Electronics Center, where he worked on developing synthetic-aperture radar. In 2003, he joined CEA-Leti as an industrial transfer manager and supervised several joint research laboratories, in particular with the multinational Michelin. In 2007, Sébastien Dauvé became a laboratory manager, then head of an R&D department in the area of sensors applied to the Internet of things and electric mobility. During this time, he supported the dissemination of new technologies in industry, including the automotive industry (Renault), aeronautics, national defense (SAFRAN), and microchips with the industry leader Intel. He played an active role in the creation of start-ups in application fields ranging from health to infrastructure security, leading to dozens of new jobs. In 2016, he became Director of the CEA-Leti Systems Division. From sensors to wireless communication, Sébastien Dauvé has played an active role in the digital transformation, focused on coupling energy frugality and performance. He has made cross-disciplinary approaches central to innovation by harnessing the expertise of talented teams with diverse backgrounds. Their goal is to provide technological tools for meeting the major societal challenges of the future. Sébastien Dauvé is a graduate of the French Ecole Polytechnique and the National Higher French Institute of Aeronautics and Space (ISAE-SUPAERO).

References

Beyond Performance: How the Semiconductor Industry and Ericsson Can Accelerate Decarbonization



G. Pozza
Networks Sales Strategy Manager & Sustainability Lead
Ericsson AB, Business Area Networks - Sales and commercial management, Stockholm, Sweden



Abstract
Artificial intelligence is driving a new wave of infrastructure investment, increasing demand for semiconductors and communications networks.
As telecom networks become more energy efficient and operational emissions decline, a larger share of the carbon footprint will come from materials, components, and manufacturing. This makes the semiconductor supply chain an increasingly important part of telecom decarbonization.
How can the semiconductor industry and Ericsson work together to reduce these emissions?
This session explores practical opportunities how the semiconductor ecosystem can help accelerate decarbonization —from renewable energy and cleaner manufacturing to reliable product-level carbon data and innovation in materials and processes.
Addressing these challenges requires collaboration across the entire ecosystem, from semiconductor manufacturers and technology suppliers to telecommunications providers and end customers.

Biography
Genevieve Pozza is a Strategy Manager & Sustainability Lead at Ericsson, where she drives the Business Area Networks environmental sustainability agenda and supports the company's ambition to achieve Net Zero emissions by 2040. Responsible for sustainability strategy execution, governance, performance management, and cross-functional transformation initiatives. With extensive leadership experience spanning strategy, product development, operational transformation, and commercial excellence, Genevieve helps drive the integration of sustainability, technology innovation, and business value creation across Ericsson's Networks operations.

References

Powering Europe’s Semiconductor Future: Energy Intelligence for Resilient, Sustainable Growth



F. Godemel
Executive Vice President Energy Management
Schneider Electric, Grenoble, France

Abstract
Europe’s semiconductor industry is entering a defining era. Demand for advanced chips is accelerating alongside AI, electrification and digitalisation, while manufacturers must strengthen resilience, expand capacity and deliver on ambitious sustainability goals. Meeting these priorities requires more than additional power. It requires a smarter approach to how energy is generated, distributed and managed, from the grid to the fab.
In this keynote, Frédéric Godemel will explore how the convergence of electrification, automation, digitalisation and AI is reshaping the energy landscape and creating new opportunities for industry. He will examine the growing relationship between the grid, AI factories and semiconductor manufacturing, and how Energy Intelligence can help turn growing energy complexity into competitive advantage.

By combining connected hardware, software-defined architectures, data, AI, services and deep domain expertise, energy systems can become more visible, intelligent and responsive. For fabs, that means improving efficiency, reliability and operational performance while reducing emissions. Frédéric will also highlight why collaboration across the semiconductor, technology and energy ecosystems will be essential to building Europe’s future industrial capacity: **resilient, efficient and sustainable by design.**

Biography
Shaping the New Energy Landscape
Frédéric's remit covers today's most urgent energy priorities, from meeting rising energy demand to strengthening energy security and sustainability. Responsible for over 80% of Schneider Electric's business, he and his teams deliver end-to-end solutions, advancing energy technology across infrastructure, data centers, buildings, and homes.
Energy intelligence for efficiency, resilience, and sustainability
By bringing together electrification, automation, digitalization and AI, Frédéric is unlocking "energy intelligence” to deliver measurable outcomes.

Revolutionary technology released under his leadership includes:
SM AirSeT, the first SF_6-free switchgear, eliminating a major greenhouse gas without compromising performance, reliability, or safety.
One Digital Grid, a unified, AI-enabled platform helping utilities reduce outage penalties by up to 20%.

The world’s first fully Software-Defined medium-voltage architecture enabling up to 3× faster ordering and manufacturing, up to 2× faster commissioning, zero-downtime upgrades, and up to 30% lower direct carbon emissions.

Frédéric also oversaw the launch of Schneider Electric's global Impact Buildings Program, leveraging its own EcoStruxure™ solutions in Schneider offices worldwide. The program launched with The NEST in Dubai, delivering a projected 37% reduction in energy consumption, followed by the Winthrop Center in North America.
In the data center space, Frédéric helps customers balance increasing compute demand with the need for greater efficiency and resilience. Today, Schneider’s technologies and expertise are trusted by 95% of the

world's hyperscale data center operators.

Accelerating progress through collaboration

With more than three decades of global industry experience, Frédéric knows that the new energy landscape won't be built in isolation. As Co-Chair of the Bloomberg Energy Tech Coalition, he convenes decision makers and experts worldwide to accelerate the adoption of demand-side technologies that drive greater energy efficiency.

References

Semiconductor & Electronics Opportunities in India



S. Keskar
CEO
Arvind Consultancy, Bangalore, India

Abstract
Coming Soon

Biography
Sanjeev Keskar is Chief Executive Officer of Arvind Consultancy. After his successful stint of 35 years in corporate world, out of which about 29 years in semiconductor industry, Mr. Keskar incorporated Arvind Consultancy, an advisory firm in the field of developing High Value-Added Eco- System for Semiconductor and Electronics Industry in India in Nov. 2020.
Prior to this, Mr. Keskar was Managing Director India at Arrow Electronics for India, a leading electronic component global distribution company for five and half years. Earlier he was Managing Director Sales at PMC-Sierra for India and SEA.
He was also elected Chairman of IESA (India Electronics and Semiconductor Association) for year 2013-14 and in current year he is part of Executive Council of IESA.
Prior to PMC Sierra, he was Country Manager, Sales, at Freescale Semiconductor (Motorola) for 5 years and Country Manager, India, for AMD Far East Ltd., where he started AMD India operations as the first Country Manager and established AMD India.
Mr. Keskar has also worked at National Semiconductor as Country Manager and at Max India Ltd. as Regional Manager.
Mr. Keskar is Professor of Practice at IIT Roorkee. Mr. Keskar is also Executive Director at EPIC Foundation.
Mr. Keskar received a master's degree in management science in Marketing and a Bachelor's in Electronics and Communication Engineering and Technology, from Pune University.

References

The Future of Europe's Industrial Policy



M. Isabelle
CEO & Founder
european economics, Paris, France

Abstract
Europe is entering a new industrial cycle shaped by AI, computing power and strategic technologies. As globalisation gives way to resilience and sovereignty, semiconductors are becoming a foundation of Europe's future competitiveness.
This keynote will explore how Europe's industrial policy is evolving to reduce dependencies, accelerate industrial scale-up and open new opportunities for ambitious technology leaders.

Biography
Marc ISABELLE, engineer and PhD in Economics, is the founder and CEO of european economics.
Marc is a recognised expert in the public funding of strategic projects. Since 2009, he has helped 210 companies secure €46 billion in public funding for more than 250 major projects. These initiatives tackle key societal challenges - including disruptive innovation, decarbonisation, resilience and infrastructure - across a wide range of industrial sectors including microelectronics, software, telecoms, automotive, energy and environment, batteries, pharmaceuticals and biotech.
Through his extensive work with the European Commission and national authorities, Marc has actively contributed to shaping the methodologies and best practices used to assess public funding applications and their compatibility with EU regulations.

References